# Monthly LabAdviser update: 5/9 2014

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| Updated Subject  | Contributor | Link to the updated pages |
| **May 2014 survey**With answers from Danchip management to the comments from the users. | **Management @danchip** | [Surveys\_and\_statistics](http://labadviser.danchip.dtu.dk/index.php/Surveys_and_statistics) |
| **HF etch of silicon rich nitride**Etch rates in silicon rich SiN in different HF solutions has been added | **Eric Jensen and Rolf Møller-Nielsen****@Nanotech** | [Wet\_Silicon\_Oxide\_Etch\_(BHF)](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Wet_Silicon_Oxide_Etch_%28BHF%29) |
| **Cr etch rate in ICP metal** | **Erol Zekovic @Nanotech and Berit Herstrøm @danchip** | [ICP\_Metal\_Etcher/Chromium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/Chromium) |
| **E-beam resist CSAR**Further process development using CSAR | **Tine Greibe @danchip** | [Lithography/CSAR](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/CSAR) |
| **Ellipsometer**Access to ellipsometer software using remote desktop | **Berit Herstrøm @danchip**  | [Optical\_characterization#Ellipsometer\_VASE\_and\_Ellipsometer\_M-2000V](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Optical_characterization#Ellipsometer_VASE_and_Ellipsometer_M-2000V) |
| **PECVD2**Etch result for 1SiN | **Berit Herstrøm @danchip** | [Deposition\_of\_Silicon\_Nitride\_using\_PECVD#Recipes\_on\_PECVD2\_for\_deposition\_of\_silicon\_nitride\_and\_silicon\_oxynitride](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Nitride/Deposition_of_Silicon_Nitride_using_PECVD#Recipes_on_PECVD2_for_deposition_of_silicon_nitride_and_silicon_oxynitride) |
| **AOE**Two test of Barc etch in the AOE | **Berit Herstrøm @danchip** | [/Remove\_resist\_in\_the\_AOE](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/AOE_%28Advanced_Oxide_Etch%29/Remove_resist_in_the_AOE) |
| **PL Mapper**Moved to characterization entry in LAbAdviser | **Berit Herstrøm****@danchip** | [Characterization/PL\_Mapper](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/PL_Mapper) |

# Equipment Manuals updated in LabManager:

 [**Manual for LPCVD polysilicon furnace (4")**](http://d4.danchip.dtu.dk/D4Doc/book/docshow.asp?DokID=1582&sText=Manual)

[**Manual for Sputter system (LESKER)**](http://d4.danchip.dtu.dk/D4Doc/book/docshow.asp?DokID=1608&sText=Manual)

[**Manual for Critical Point Dryer**](http://d4.danchip.dtu.dk/D4Doc/book/docshow.asp?DokID=1557&sText=Manual)

[**Manual for Phosphorus Drive-in furnace (A3)**](http://d4.danchip.dtu.dk/D4Doc/book/docshow.asp?DokID=1644&sText=Manual)

[**Manual for Phosphorus Predep furnace (A4)**](http://d4.danchip.dtu.dk/D4Doc/book/docshow.asp?DokID=1646&sText=Manual)

[**Manual for furnace PC**](http://d4.danchip.dtu.dk/D4Doc/book/docshow.asp?DokID=1926&sText=Manual)

[**Manual for Boron Drive-in + Pre-dep Furnace (A1)**](http://d4.danchip.dtu.dk/D4Doc/book/docshow.asp?DokID=3189&sText=Manual)